

IRF7324TRPBF-VB Datasheet

Dual P-Channel 20V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)		
	0.018 at $V_{GS} = -4.5 \text{ V}$	- 8.9		
- 20	0.022 at V _{GS} = - 2.5 V	- 8.1		
	0.030 at V _{GS} = - 1.8 V	- 3.6		

 D_1

 D_1

 D_2

 D_2

SO-8

 G_1

 S_2

 G_2

3



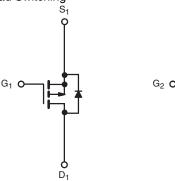


- Advanced High Cell Density Process
- Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

· Load Switching



P-Channel MOSFET

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ss otherwise r	noted			
Parameter		Symbol	10 s	Steady State	Unit	
Drain-Source Voltage		V _{DS}	- 20		V	
Gate-Source Voltage		V _{GS}	± 12			
Continuous Dunin Courset (T. 150 °C)	T _A = 25 °C	1	- 8.9 - 6.7	- 6.7		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C	'D	- 7.1	- 5.4		
Pulsed Drain Current		I _{DM}	- 30		Α	
Continuous Source Current (Diode Conduction) ^a		I _S	- 1.7	- 0.9		
	T _A = 25 °C	P _D	2.0	1.1	W	
Maximum Power Dissipation ^a	T _A = 70 °C	1.3		0.7	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55	to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Manipulation to Applicable	t ≤ 10 s	R _{thJA}	46	62.5	
Maximum Junction-to-Ambient ^a	Steady State	□thJA	80	110	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	24	32	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.



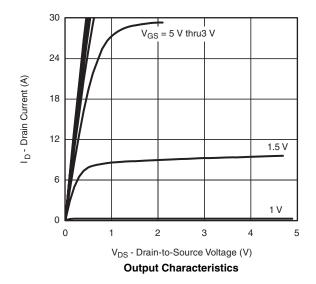
Parameter	Symbol	Test Conditions		Тур.	Max.	Unit
Static				•		
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -350 \mu A$	- 0.4		- 1.0	V
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 8 V			± 100	nA
7 0	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V	-1		- 1	μА
Zero Gate Voltage Drain Current		V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C			- 5	
On-State Drain Current ^a I _{D(on)} V _{DS} = - 5 V, V _{GS} = - 4.5 V		- 30			Α	
		V _{GS} = - 4.5 V, I _D = - 8.9 A	0.018			Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 8.1 A	8.1 A 0.022			
		V _{GS} = - 1.8 V, I _D = - 3.6 A		0.030		1
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 8.9 A		26		S
Diode Forward Voltage ^a	V_{SD}	I _S = - 1.7 A, V _{GS} = 0 V		- 0.7	- 1.2	V
Dynamic ^b						
Total Gate Charge	Q_g			34.5	52	
Gate-Source Charge	Q_{gs}	V _{DS} = - 10 V, V _{GS} = - 4.5 V, I _D = - 8.9 A		5.1		nC
Gate-Drain Charge	Q_{gd}			9.6		
Gate Resistance	R_g			9		Ω
Turn-On Delay Time	t _{d(on)}			25	40	
Rise Time	t _r	V_{DD} = - 10 V, R_L = 6 Ω		46	70	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 6 Ω		230	345	ns
Fall Time	t _f			155	235	
Source-Drain Reverse Recovery Time t_{rr} $I_F = -1.7 \text{ A}$, $dI/dt = 100 \text{ A/}\mu\text{s}$		I _F = - 1.7 A, dI/dt = 100 A/μs		128	200	

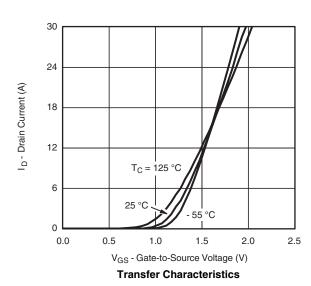
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

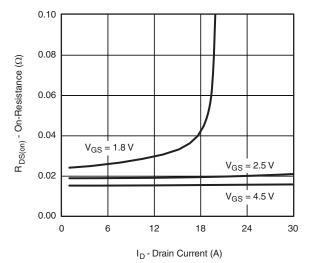
TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



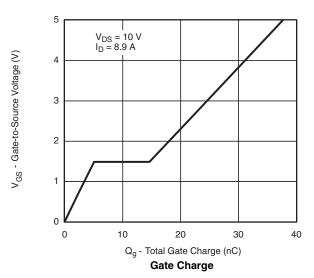




TYPICAL CHARACTERISTICS 25 °C unless otherwise noted

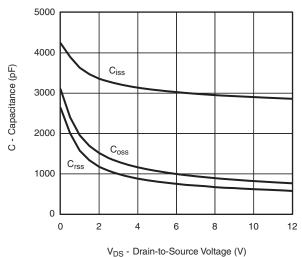


On-Resistance vs. Drain Current



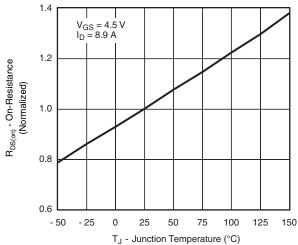
30 $T_J = 150 \, ^{\circ}C$ 10 T_J = 25 °C 0.0 0.2 0.4 0.6 0.8 1.0 1.2 1.4 V_{SD} - Source-to-Drain Voltage (V)

Source-Drain Diode Forward Voltage

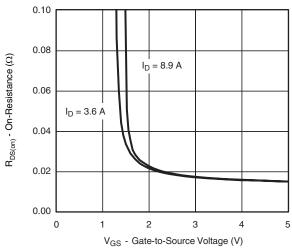


Capacitance





On-Resistance vs. Junction Temperature

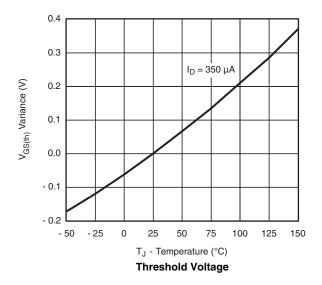


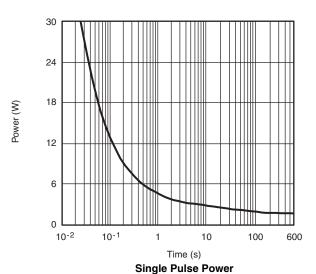
On-Resistance vs. Gate-to-Source Voltage

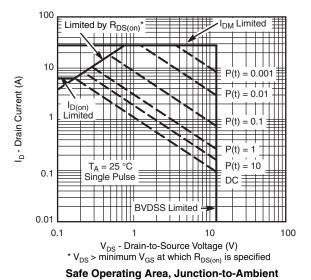
Is - Source Current (A)

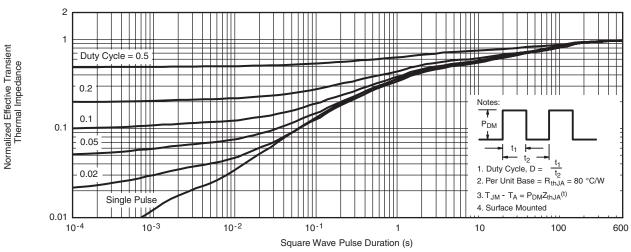


TYPICAL CHARACTERISTICS 25 °C unless otherwise noted





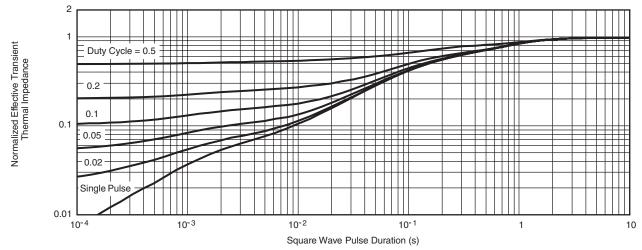




Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C unless otherwise noted

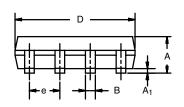


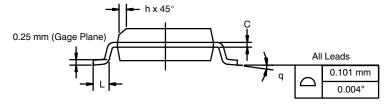
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
FCN: C-06527-Rev. I. 11-Sep-06						

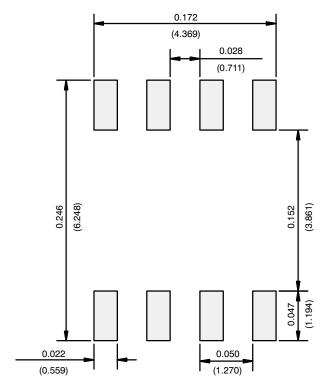
ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498

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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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